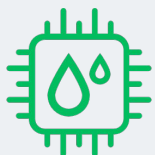


COMINO MOBO (AMD RYZEN™ THREADRIPPER™) WCB SET for ASUS ZENITH II EXTREME / EXTREME ALPHA with VRM coldplate, Cu-Steel

KEY ADVANTAGES



High quality liquid cooling
of the CPU and the VRM
modules on the motherboard



Designed for AMD SP3/TR4
socket and ASUS Zenith II
Extreme / Extreme Alpha
MoBo



High efficient deformational
cutting technology for
micro-fins (0.25mm x 2.7mm)
manufacturing



Thermally-tested and quality
guaranteed. Low ΔT° between
the chip and inlet coolant
temperatures is assured



Heat dissipation increased
up to 10 times as compared
to the air-cooling



Only non-corrosive materials
(Copper, Stainless Steel,
Plastic)

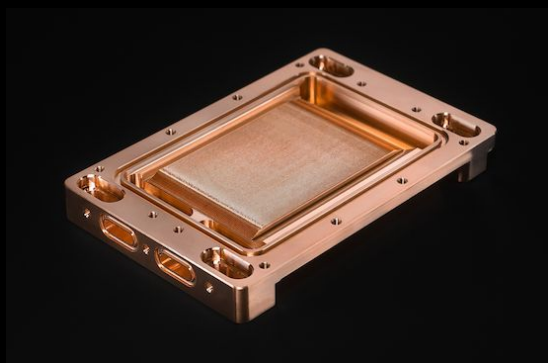
COMINO WATERBLOCKS TECHNOLOGY

The Comino liquid-cooling system is based on the deformational cutting technology that allows to transfer more heat from the source than you would normally expect with direct liquid cooling.

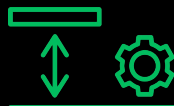
This unique technology allows to create a copper fin as thin as 0.1mm with 0.1mm channel and 3mm height. In Comino solution microfins are optimized for low pressure drop with the thickness of 0.25mm, channel - 0.25mm and 2.7mm height.

Large increase (up to 12 times) of the waterblock surface area that contacts with the coolant allows faster heat dissipation. It prevents thermal throttling of CPU and GPU keeping temperatures within a safe range even at 24/7 operation in harsh environment.

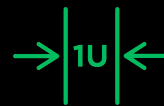
This advantage makes our waterblocks extremely efficient (low ΔT°) and cost-effective.



- Use the same CPU waterblock with different motherboards.
- Unique design for the CPU waterblocks with inter-changeable VRM cold-plates.



- Ultimate cooling for each and every CPU.
- Level-varied VRM coldplates to achieve perfect contact patch and heat transfer.

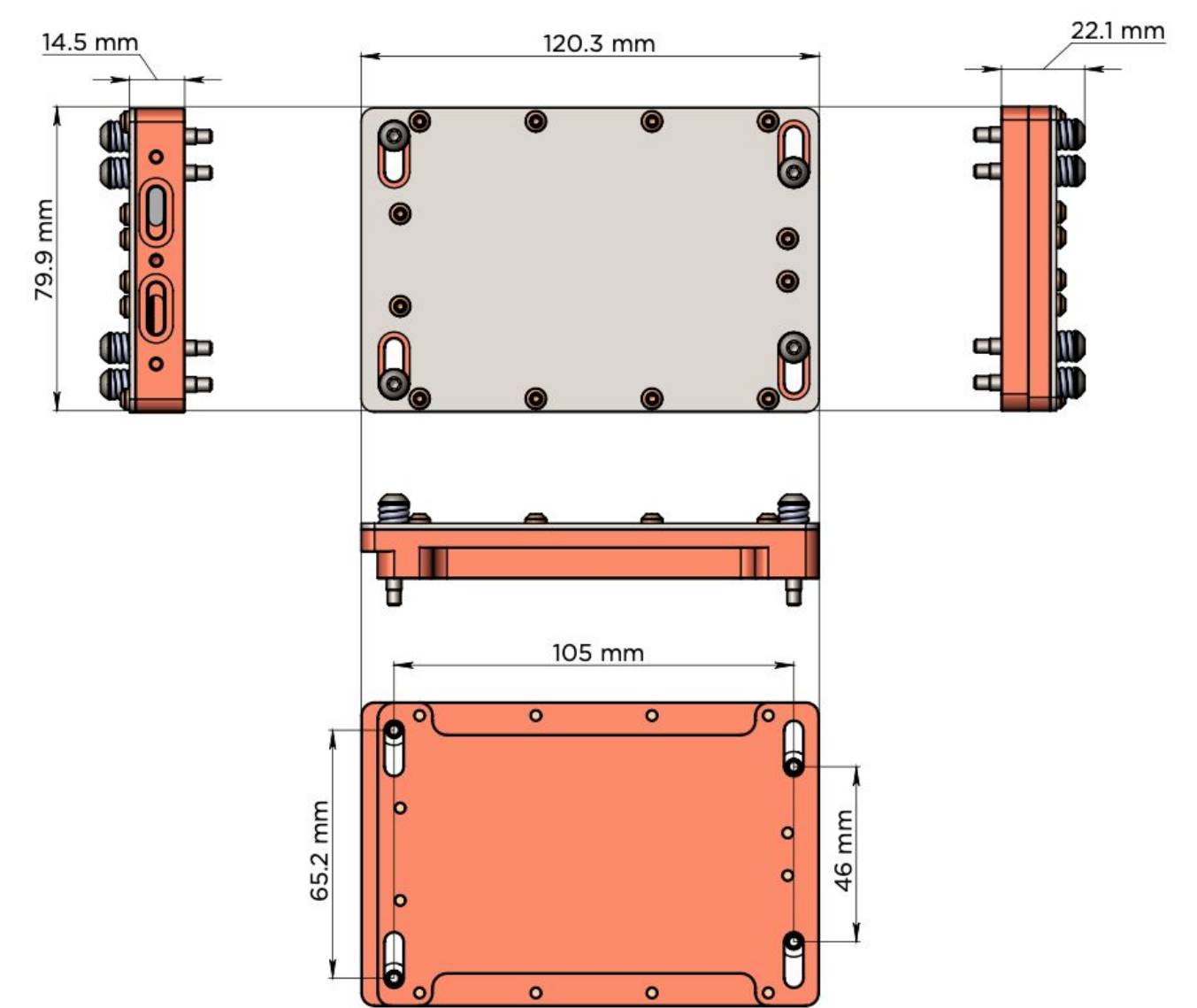


- Slim waterblock design can be used in 1U servers.

OVERALL DIMENSIONS

Core Block

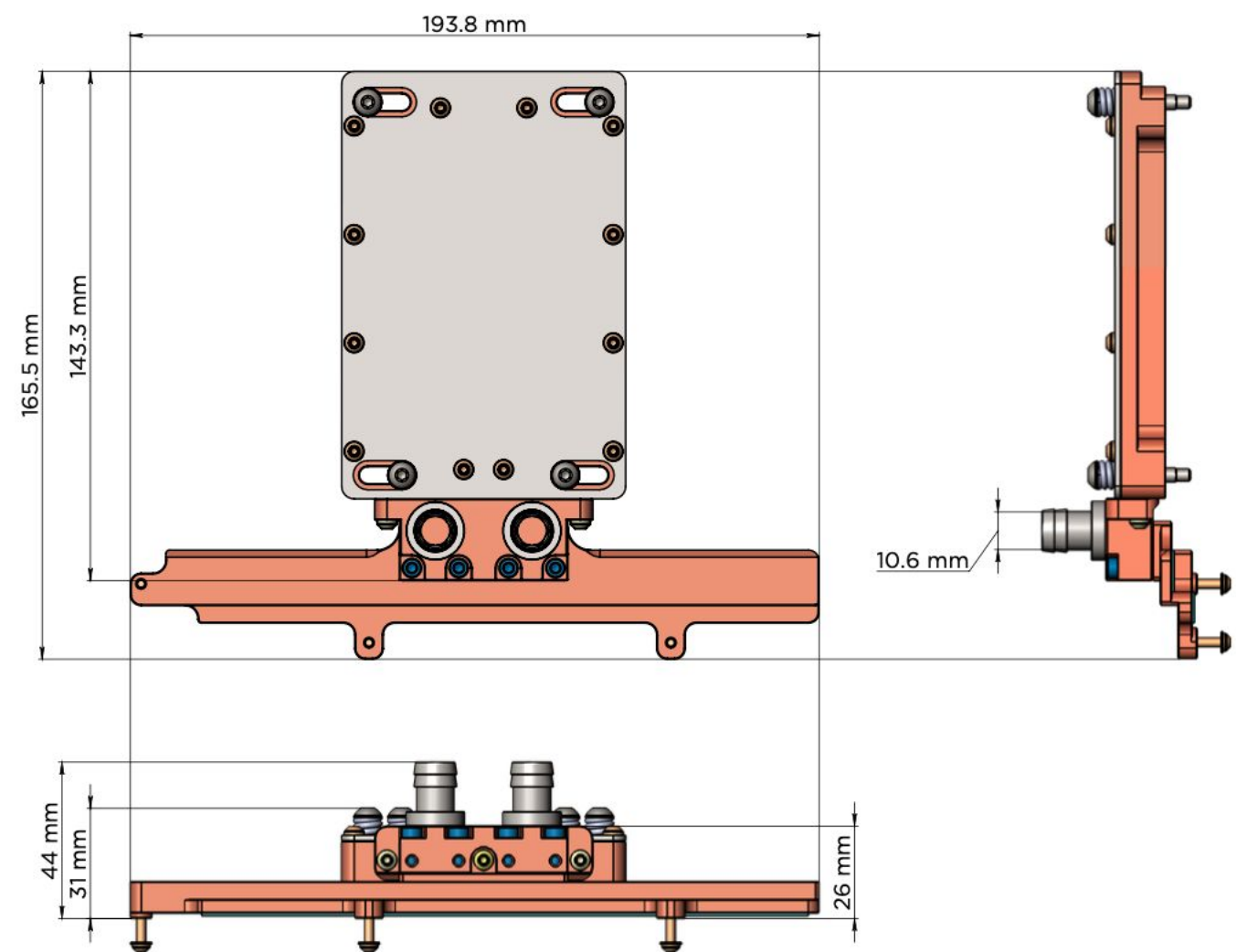
ID	Name	Release version	Release date
4615	WCB CPU (Socket TR4/SP3) GEN3 Core kit	A.01	August, 2021



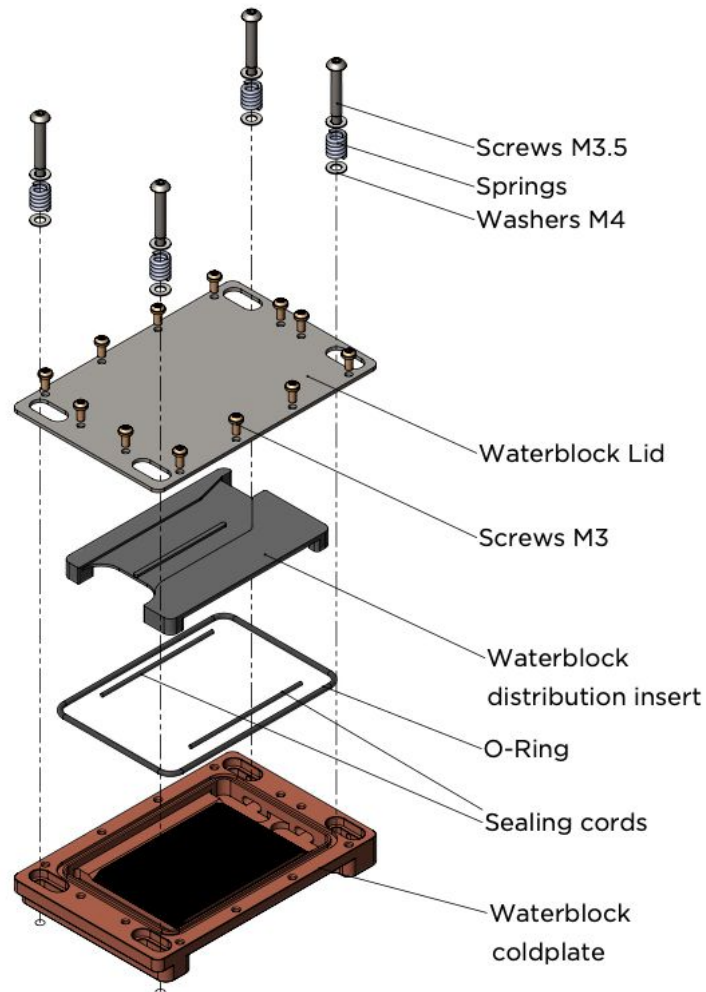
OVERALL DIMENSIONS

MoBo Water Cooling Block Set

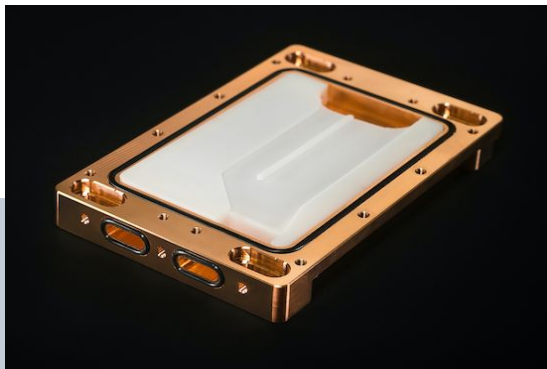
ID	Name		Release version	Release date
5531	Comino MoBo (AMD Ryzen™ Threadripper™) WCB Set for ASUS Zenith II Extreme / Extreme Alpha with VRM coldplate, Cu-Steel		–	April, 2022
	4615	CORE BLOCK / WCB CPU (Socket TR4/SP3) GEN3 Core kit	A.01	August, 2021
	4628	VRM KIT / WCB MB (ASUS ZIIEA) Kit / w fittings /w mount kit / w VRM	A.01	August, 2021



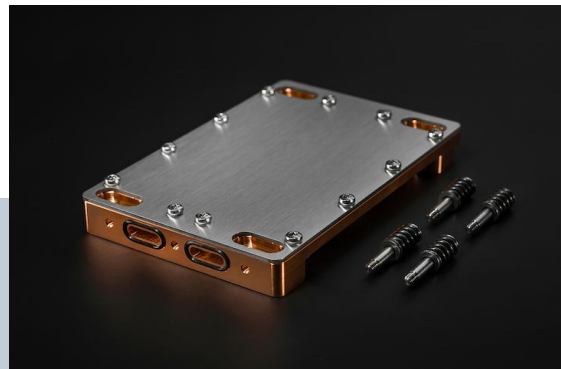
CORE BLOCK ASSEMBLY



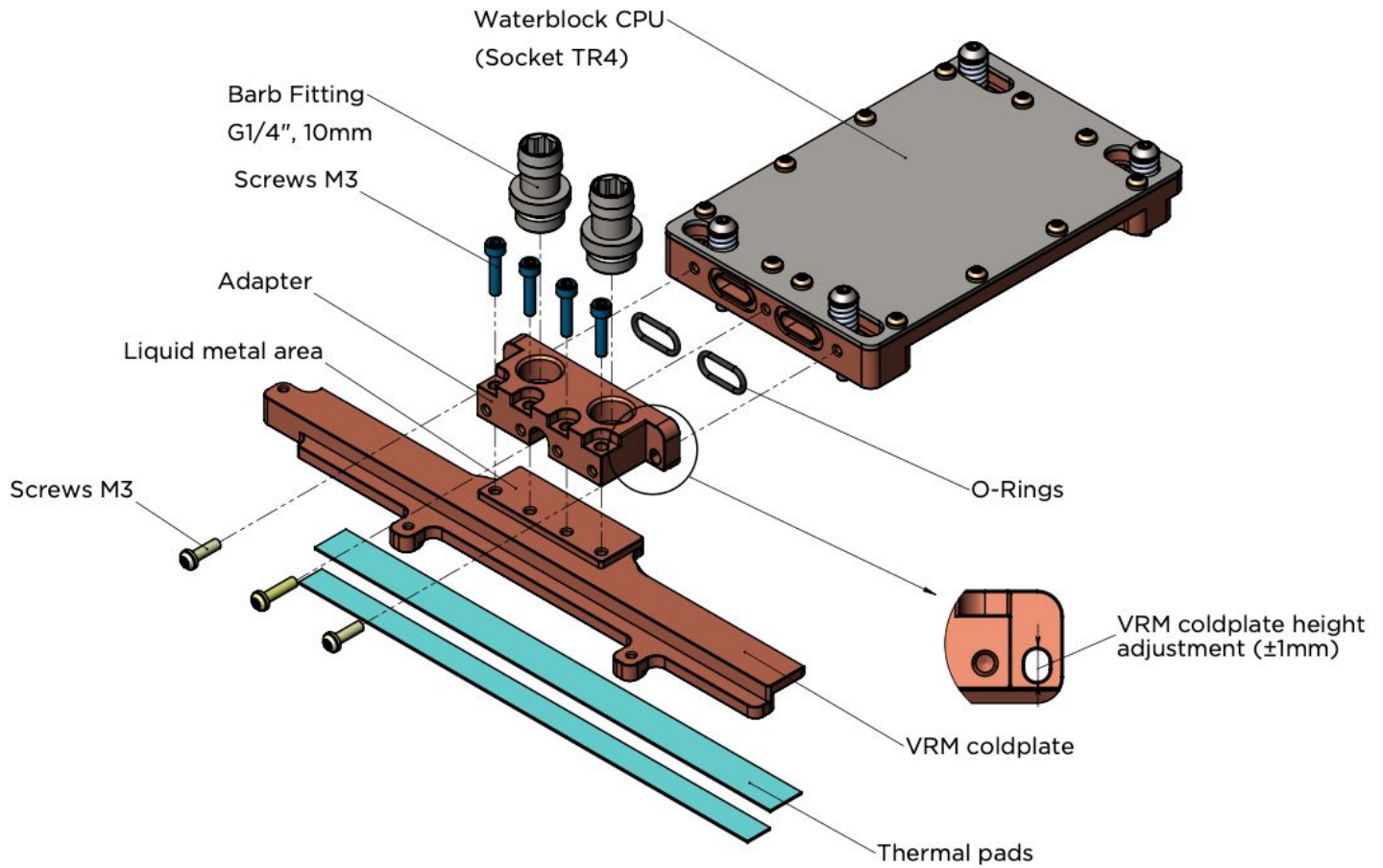
Open View



Assembled View



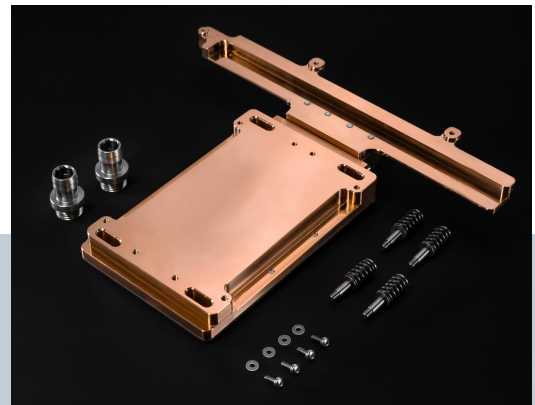
WATERBLOCK ASSEMBLY



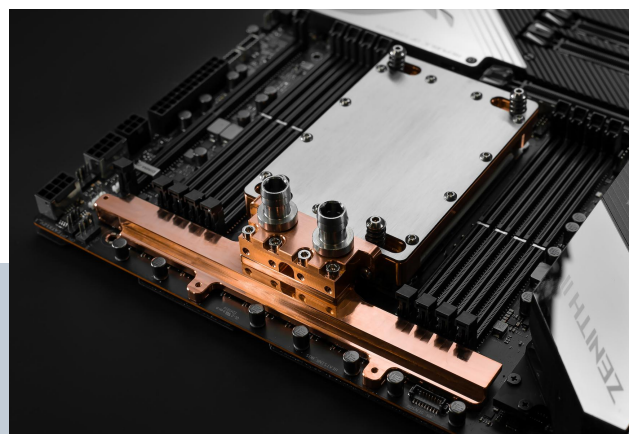
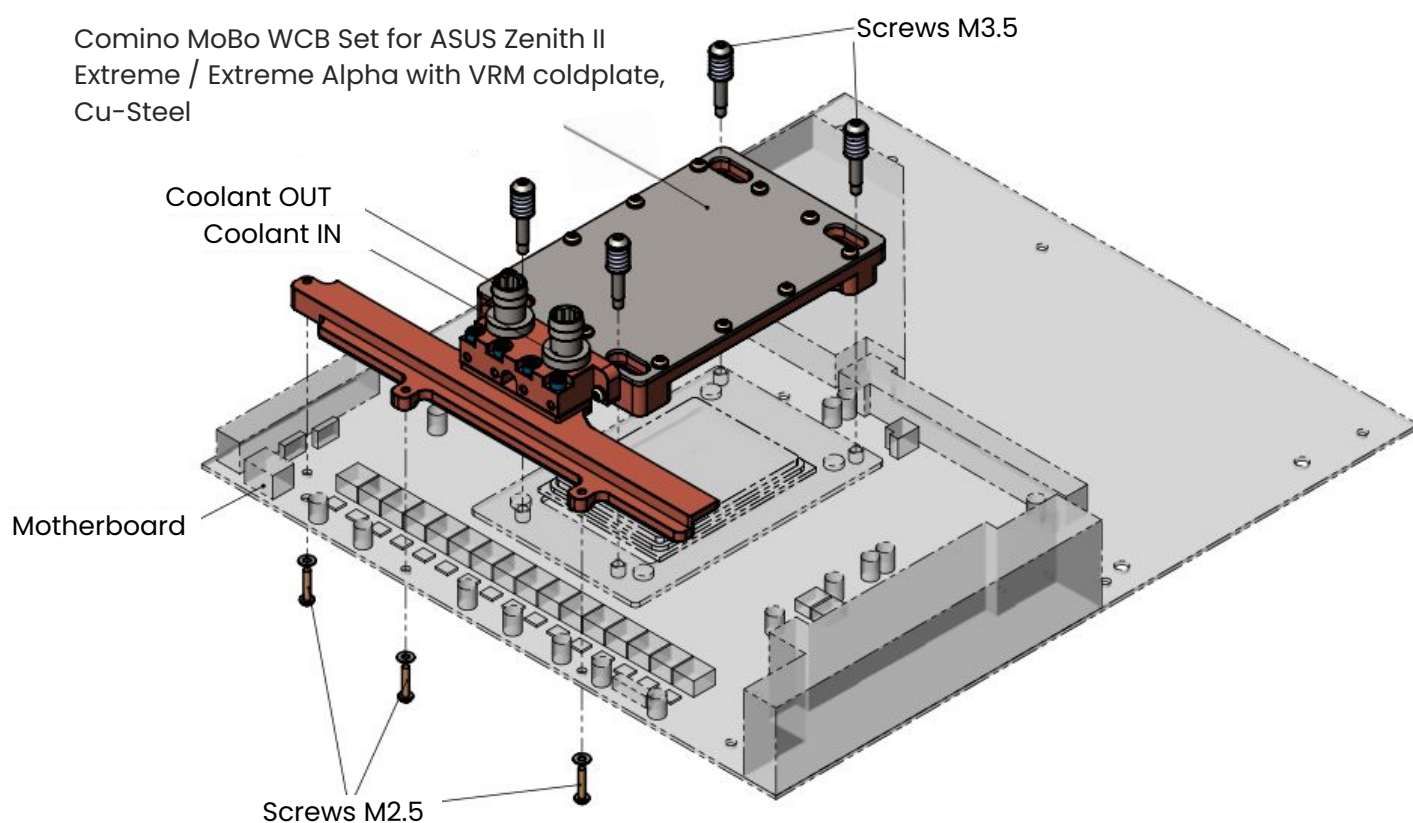
Top View



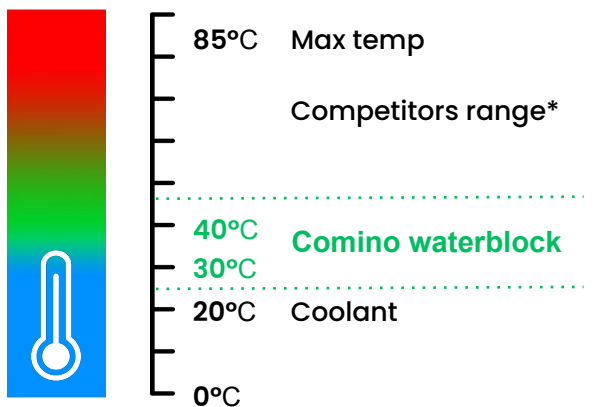
Bottom View



WATERBLOCK INSTALLATION



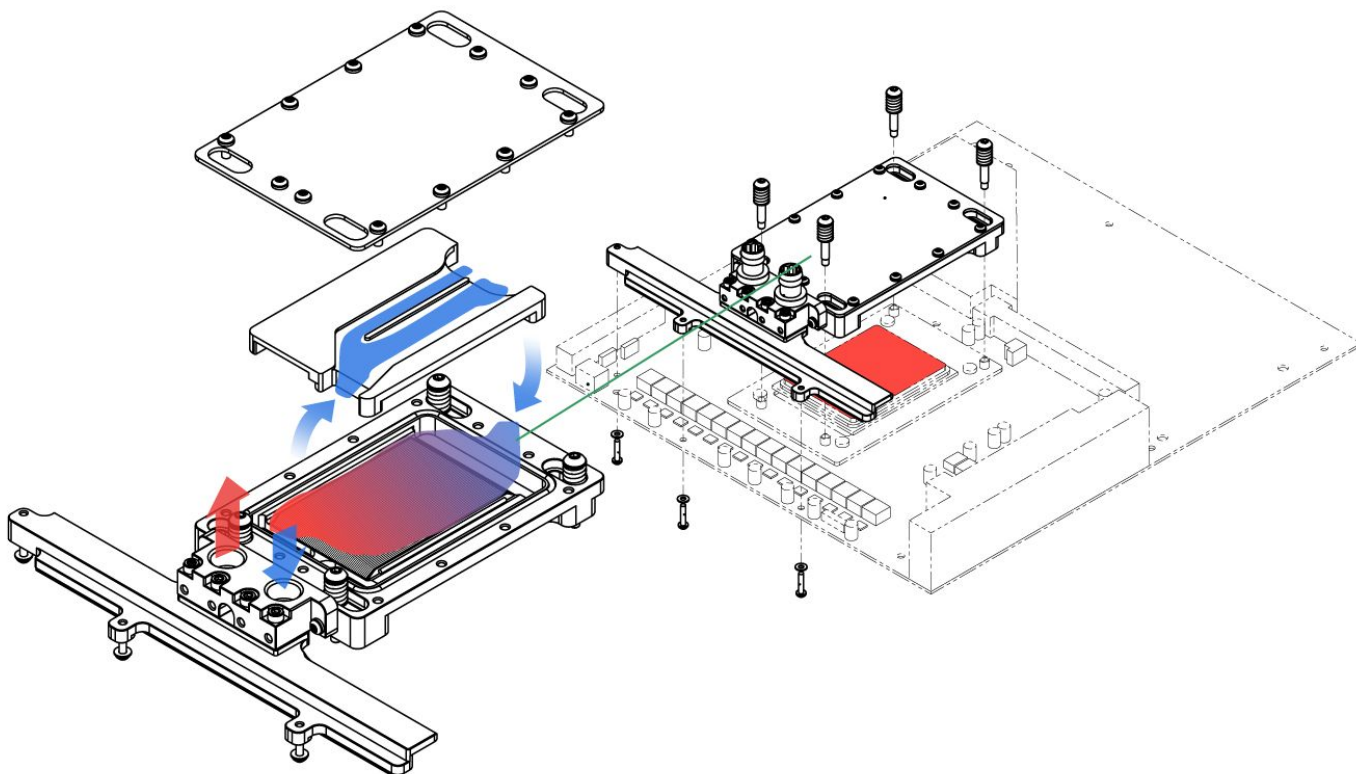
THERMAL PERFORMANCE – BEST IN CLASS



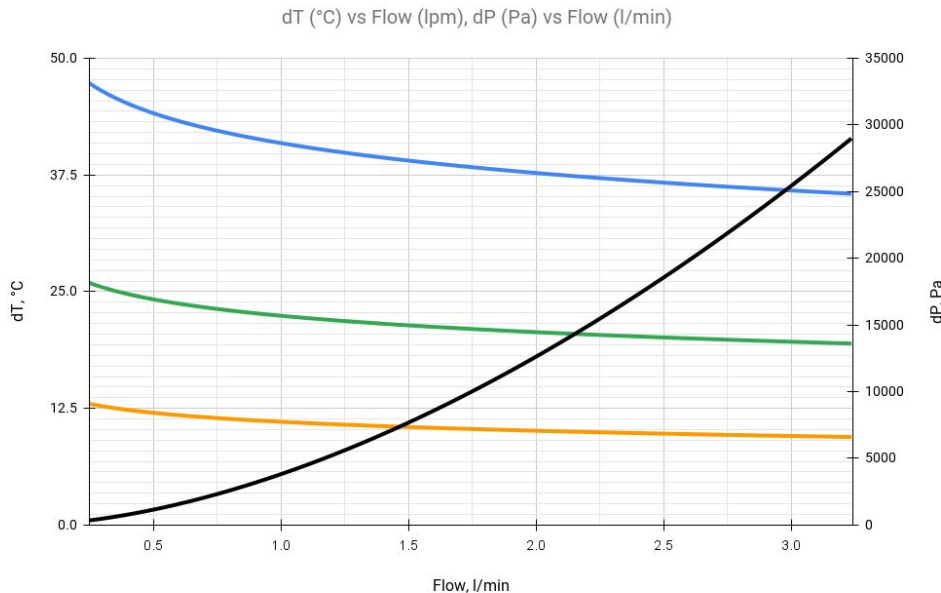
* — For the same coolant flow

Comino waterblock technology ensures low ΔT° between the chip and inlet coolant temperatures.

- At coolant temperature of 20°C, the temperature of the chips with Comino waterblocks will be **30°-40°C**.
- The temperature of the chips with competitors waterblocks for the same coolant flow might rise up to 85°C.

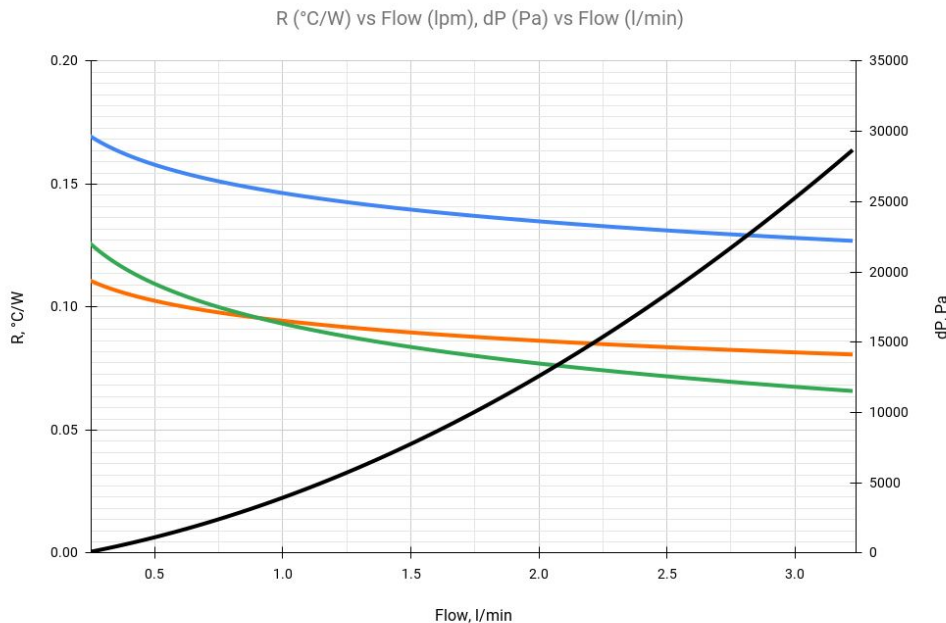


THERMAL RESISTANCE (CPU-WATER INLET), TEMPERATURE RISE and PRESSURE DROP vs FLOW RATE



Waterblock thermal resistance (°C/W) and coolant pressure drop (Pa) between inlet and outlet of waterblock vs coolant flow rate (l/min).

- EPYC 7252, 8 Core / 16 Threads, 2.8/3.2 GHz, / w VRM (GIGABYTE MZ72-HB0), 117W
- Threadripper PRO 3975WX, 32 Core / 64 Threads, 3.5/4.2 GHz, / w VRM (MoBo GIGABYTE WRX80-SU8), 279W
- Threadripper PRO 3995WX, 64 Core / 128 Threads, 2.7/4.2 GHz, / w VRM (MoBo GIGABYTE WRX80-SU8), 279W
- dP, Pa



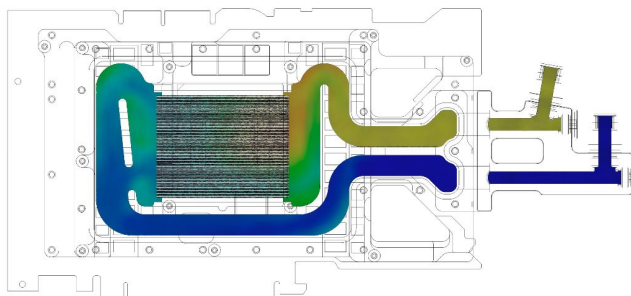
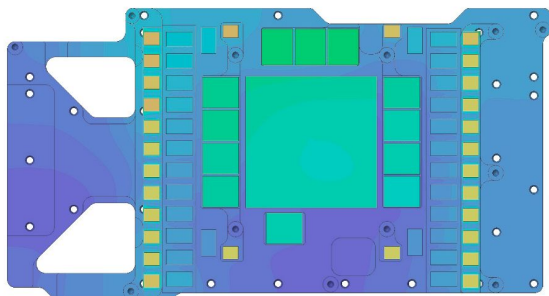
Temperature rise of CPU processor p-n junction relatively to coolant inlet temperature and coolant pressure drop (Pa) between inlet and outlet of waterblock vs coolant flow rate (l/min)

* — Thermal resistance research for other CPU models available upon request

WE KNOW HOW TO BEAT THE HEAT

Comino provides RnD upon request, including product design with a series of complex thermodynamic calculations and a variety of stress tests supported by thermal analysis.

- Tailored liquid-cooling system and solution for your needs.
- OEM & ODM cooperation. Thermal design, prototyping, PoC, manufacturing, QA, supply.
- Creating a unique customization of hardware components and liquid-cooling systems.
- Design & Manufacturing of devices and cooling components for range of industry applications from scratch.



ADDITIONAL INFORMATION

Check the compatibility and find the composition of the kit on the waterblock product page

<https://faq.comino.com/en/waterblocks/main>



CONTACTS

For more product information visit: www.comino.com

Email us info@comino.com



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